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Abstract

Device for placing flip chips on a substrate

A freely positionable placement head (1) removes presented flip chips (6) from a wafer (5), the connection side of said chips being directed upward. The placement head has a turning device (9), in which, by the time they are placed onto a substrate (8) to be provided with placed components, the flip chips are turned in such a way that they can be placed with their connection side onto the substrate.

This makes it possible to dispense with a complex turning device assigned to the wafer (5).

Figure 1